

ISSUE CLASSIFICATION	CLASS	STATUS
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PATENT NUMBER

U.S. UTILITY Patent Application

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PATENT DATE

APPLICATION NO. 09/800495	CONT/PRIOR F	CLASS 451-499	SUBCLASS 608	ART UNIT 3723	EXAMINER DV NGUYEN
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TITLE
Method of detecting and measuring endpoint of polishing processing and its apparatus and method of manufacturing semiconductor device using the same

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____ _____ _____	_____ (Primary Examiner) (Date)			ISSUE FEE	
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